DATA SHEET

80C562/83C562
Single-chip 8-bit microcontroller

Product specification

IC20 Data Handbook

1992 Jan 08

Philips
Semiconductors

PHILIPS

Single-chip 8-bit microcontroller 80C562/83C562

Single-chip 8-bit microcontroller with 8-bit A/D, capture/compare timer, high-speed outputs, PWM

DESCRIPTION

The 80C562/83C562 (hereafter generically referred to as 8XC562) Single-Chip 8-Bit Microcontroller is manufactured in an advanced CMOS process and is a derivative of the 80C51 microcontroller family. The 83C562/83C562 has the same instruction set as the 80C51.

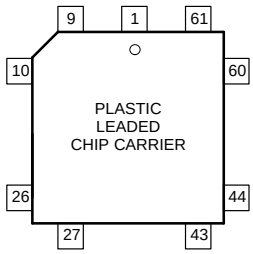
The 8XC562 contains a non-volatile 256 × 8 read-only program memory, a volatile 256 × 8 read/write data memory (83C562) (the 80C562 is ROMless), a volatile 256 × 8 read/write data memory, six 8-bit I/O ports, two 16-bit timer/event counters (identical to the timers of the 80C51), an additional 16-bit timer coupled to capture and compare latches, a 15-source, two-priority-level, nested interrupt structure, an 8-input ADC, two pulse width modulated outputs, standard 80C51 UART, a “watchdog” timer and on-chip oscillator and timing circuits. For systems that require extra capability, the 83C562 can be expanded using standard TTL compatible memories and logic.

The device also functions as an arithmetic processor having facilities for both binary and BCD arithmetic plus bit-handling capabilities. The instruction set consists of over 100 instructions: 49 one-byte, 45 two-byte and 17 three-byte. With a 12MHz crystal, 58% of the instructions are executed in 1µs and 40% in 2µs. Multiply and divide instructions require 4µs.

FEATURES

- 80C51 instruction set
- 8k × 8 ROM expandable externally to 64k bytes
- 256 × 8 RAM, expandable externally to 64k bytes
- Two standard 16-bit timer/counters
- An additional 16-bit timer/counter coupled to four capture registers and three compare registers
- Capable of producing eight synchronized, timed outputs
- An 8-bit ADC with eight multiplexed analog inputs
- Two 8-bit resolution, pulse width modulated outputs
- Five 8-bit I/O ports plus one 8-bit input port shared with analog inputs
- Full-duplex UART compatible with the standard 80C51
- On-chip watchdog timer
- Three temperature ranges
  - 0 to +70°C
  - –40 to +85°C
  - –40 to +125°C

PIN CONFIGURATION



Pin	Function	Pin	Function
1	P5.0/ADC0	35	XTAL1
2	V_{DD}	36	V_{SS}
3	STADC	37	V_{SS}
4	$\overline{PWM0}$	38	NC
5	$\overline{PWM1}$	39	P2.0/A08
6	$\overline{EW}$	40	P2.1/A09
7	P4.0/CMSR0	41	P2.2/A10
8	P4.1/CMSR1	42	P2.3/A11
9	P4.2/CMSR2	43	P2.4/A12
10	P4.3/CMSR3	44	P2.5/A13
11	P4.4/CMSR4	45	P2.6/A14
12	P4.5/CMSR5	46	P2.7/A15
13	P4.6/CMT0	47	$\overline{PSEN}$
14	P4.7/CMT1	48	ALE
15	RST	49	$\overline{EA}$
16	P1.0/CT0I	50	P0.7/AD7
17	P1.1/CT1I	51	P0.6/AD6
18	P1.2/CT2I	52	P0.5/AD5
19	P1.3/CT3I	53	P0.4/AD4
20	P1.4/T2	54	P0.3/AD3
21	P1.5/RT2	55	P0.2/AD2
22	P1.6	56	P0.1/AD1
23	P1.7	57	P0.0/AD0
24	P3.0/RxD	58	AVref–
25	P3.1/TxD	59	AVref+
26	P3.2/$\overline{INT0}$	60	AV_{SS}
27	P3.3/$\overline{INT1}$	61	AV_{DD}
28	P3.4/T0	62	P5.7/ADC7
29	P3.5/T1	63	P5.6/ADC6
30	P3.6/$\overline{WR}$	64	P5.5/ADC5
31	P3.7/$\overline{RD}$	65	P5.4/ADC4
32	NC	66	P5.3/ADC3
33	NC	67	P5.2/ADC2
34	XTAL2	68	P5.1/ADC1

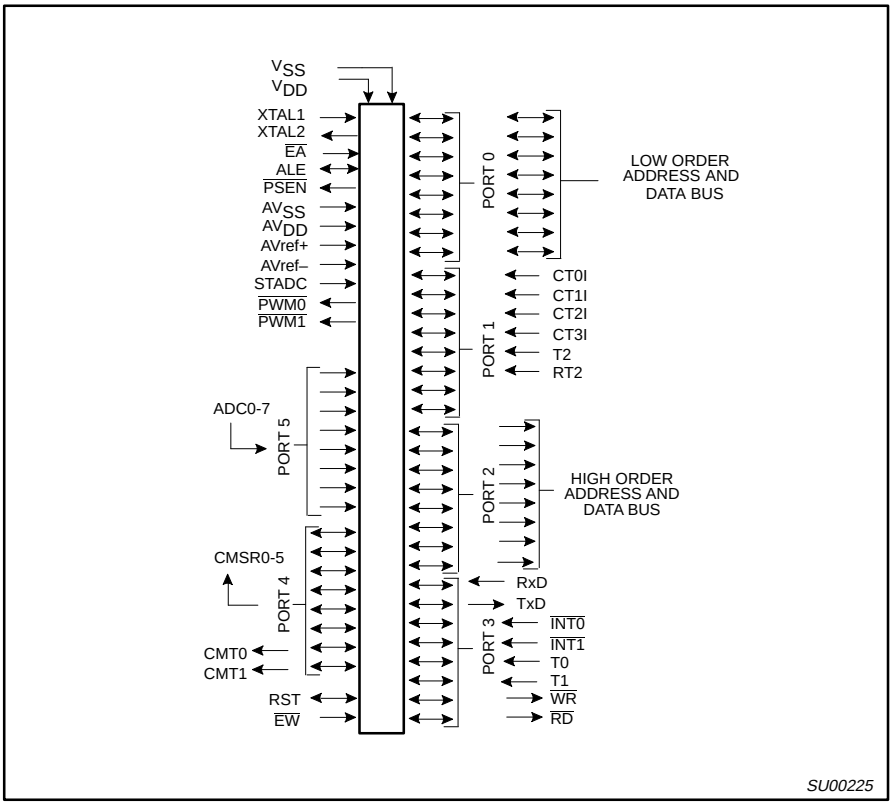
SU00224

ORDERING INFORMATION

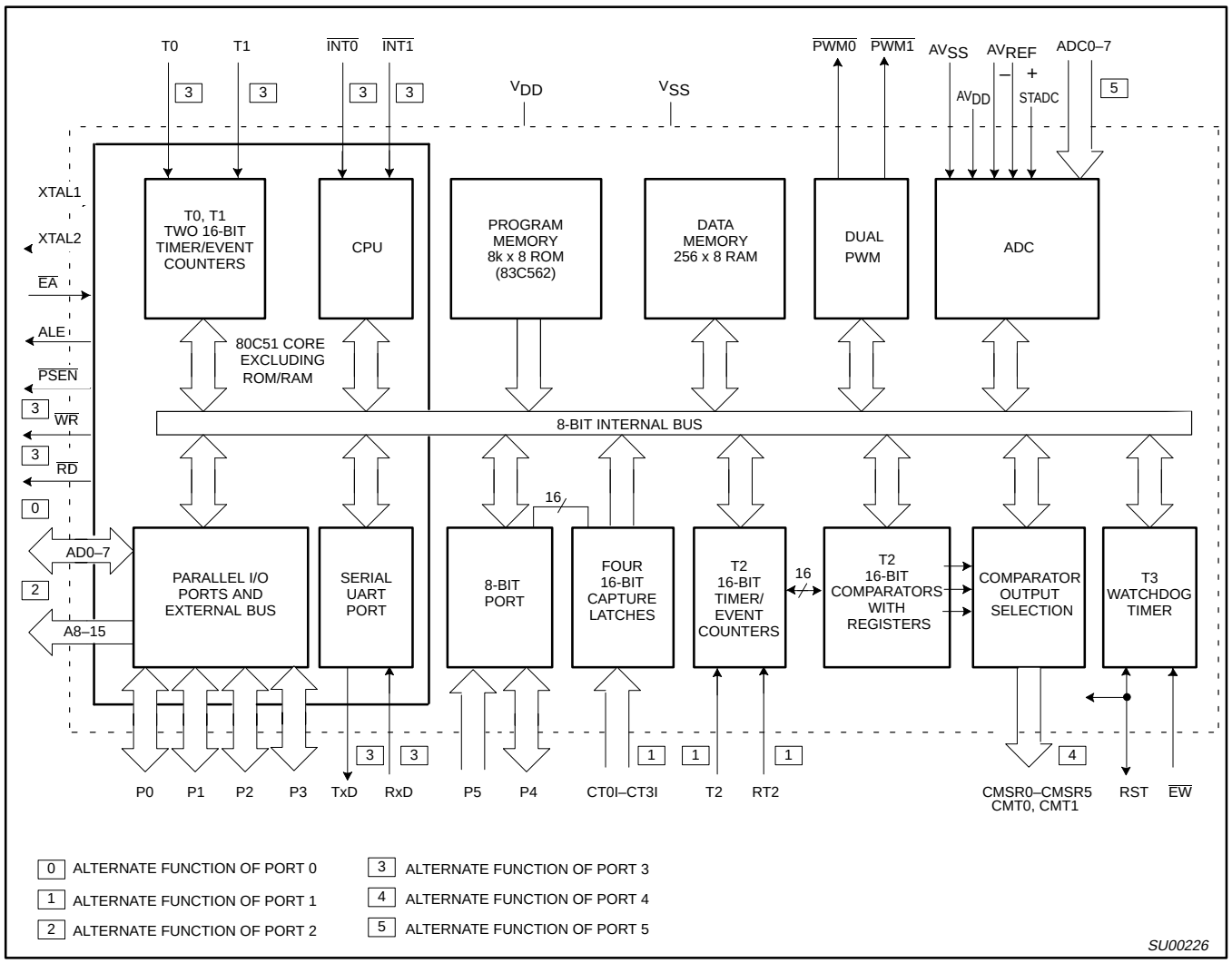
PHILIPS PART ORDER NUMBER PART MARKING		PHILIPS NORTH AMERICA PART ORDER NUMBER					TEMPERATURE RANGE °C	
ROMless	ROM	ROMless	ROM	Drawing Number	EPROM	Drawing Number	AND PACKAGE	FREQ MHz
PCB80C562-16WP	PCB83C562-16WP/xxx	S80C562-4A68	S83C562-4A68	SOT188	S87C552-4A68[2]	SOT188-3	0 to +70, Plastic Leaded Chip Carrier	16
					S87C552-4K68[2]	1473A	0 to +70, Plastic Leaded Chip Carrier w/Window	16
PCF80C562-12WP	PCF83C562-12WP/xxx	S80C562-2A68	S83C562-2A68	SOT188	S87C552-5A68[2]	SOT188-3	–40 to +85, Plastic Leaded Chip Carrier	12
					S87C552-5K68[2]	1473A	–40 to +85, Plastic Leaded Chip Carrier w/Window	12
PCA80C562-12WP	PCA83C562-12WP/xxx	S80C562-6A68	S83C562-6A68	SOT188			–40 to +125, Plastic Leaded Chip Carrier	12

NOTES:
1. 80C562 and 83C562 frequency range is 1.2MHz–12MHz or 1.2MHz–16MHz.
2. 87C552 frequency range is 3.5MHz–16MHz. For full specification, see the 87C552 data sheets.
3. xxx denotes the ROM code number.

LOGIC SYMBOL



BLOCK DIAGRAM



PIN DESCRIPTION

MNEMONIC	PIN NO.	TYPE	NAME AND FUNCTION
V_{DD}	2	I	**Digital Power Supply:** +5V power supply pin during normal operation, idle and power-down mode.
STADC	3	I	**Start ADC Operation:** Input starting analog to digital conversion (ADC operation can also be started by software).
$\overline{PWM0}$	4	O	**Pulse Width Modulation:** Output 0.
$\overline{PWM1}$	5	O	**Pulse Width Modulation:** Output 1.
$\overline{EW}$	6	I	**Enable Watchdog Timer:** Enable for T3 watchdog timer and disable power-down mode.
P0.0–P0.7	57–50	I/O	**Port 0:** Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application it uses strong internal pull-ups when emitting 1s.
P1.0–P1.7	16–23	I/O	**Port 1:** 8-bit I/O port. Alternate functions include:
	16–23	I/O	**(P1.0–P1.7):** Quasi-bidirectional port pins.
	16–19	I/O	**CT0I–CT3I (P1.0–P1.3):** Capture timer input signals for timer T2.
	20	I	**T2 (P1.4):** T2 event input
	21	I	**RT2 (P1.5):** T2 timer reset signal. Rising edge triggered.
P2.0–P2.7	39–46	I/O	**Port 2:** 8-bit quasi-bidirectional I/O port. Alternate function: High-order address byte for external memory (A08–A15).
P3.0–P3.7	24–31	I/O	**Port 3:** 8-bit quasi-bidirectional I/O port. Alternate functions include:
	24		**RxD(P3.0):** Serial input port.
	25		**TxD (P3.1):** Serial output port.
	26		**$\overline{INT0}$ (P3.2):** External interrupt.
	27		**$\overline{INT1}$ (P3.3):** External interrupt.
	28		**T0 (P3.4):** Timer 0 external input.
	29		**T1 (P3.5):** Timer 1 external input.
	30		**$\overline{WR}$ (P3.6):** External data memory write strobe.
	31		**$\overline{RD}$ (P3.7):** External data memory read strobe.
P4.0–P4.7	7–14	I/O	**Port 4:** 8-bit quasi-bidirectional I/O port. Alternate functions include:
	7–12	O	**CMSR0–CMSR5 (P4.0–P4.5):** Timer T2 compare and set/reset outputs on a match with timer T2.
	13, 14	O	**CMT0, CMT1 (P4.6, P4.7):** Timer T2 compare and toggle outputs on a match with timer T2.
P5.0–P5.7	68–62, 1	I	**Port 5:** 8-bit input port. **ADC0–ADC7 (P5.0–P5.7):** Alternate function: Eight input channels to ADC.
RST	15	I/O	**Reset:** Input to reset the 87C552. It also provides a reset pulse as output when timer T3 overflows.
XTAL1	35	I	**Crystal Input 1:** Input to the inverting amplifier that forms the oscillator, and input to the internal clock generator. Receives the external clock signal when an external oscillator is used.
XTAL2	34	O	**Crystal Input 2:** Output of the inverting amplifier that forms the oscillator. Left open–circuit when an external clock is used.
V_{SS}	36, 37	I	**Digital ground.**
$\overline{PSEN}$	47	O	**Program Store Enable:** Active-low read strobe to external program memory.
ALE	48	O	**Address Latch Enable:** Latches the low byte of the address during accesses to external memory. It is activated every six oscillator periods. During an external data memory access, one ALE pulse is skipped. ALE can drive up to eight LS TTL inputs and handles CMOS inputs without an external pull-up.
$\overline{EA}$	49	I	**External Access:** When $\overline{EA}$ is held at TTL level high, the CPU executes out of the internal program ROM provided the program counter is less than 8192. When $\overline{EA}$ is held at TTL low level, the CPU executes out of external program memory. $\overline{EA}$ is not allowed to float.
AV_{REF-}	58	I	**Analog to Digital Conversion Reference Resistor:** Low-end.
AV_{REF+}	59	I	**Analog to Digital Conversion Reference Resistor:** High-end.
AV_{SS}	60	I	**Analog Ground**
AV_{DD}	61	I	**Analog Power Supply**

NOTE:
1. To avoid “latch-up” effect at power-on, the voltage on any pin at any time must not be higher or lower than V_{DD} +0.5V or V_{SS} – 0.5V, respectively.

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator, as shown in the logic symbol.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

RESET

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To ensure a good power-on reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-on, the voltage on V_{DD} and RST must come up at the same time for a proper start-up.

IDLE MODE

In the idle mode, the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

POWER-DOWN MODE

In the power-down mode, the oscillator is stopped and the instruction to invoke power-down is the last instruction executed. Only the contents of the on-chip RAM are preserved. A hardware reset is the only way to terminate the power-down mode. the control bits for the reduced power modes are in the special function register PCON. Table 1 shows the state of the I/O ports during low current operating modes.

Table 1. External Pin Status During Idle and Power-Down Modes

MODE	PROGRAM MEMORY	ALE	$\overline{\text{PSEN}}$	PORT 0	PORT 1	PORT 2	PORT 3	PORT 4	PWM0/ PWM1
Idle	Internal	1	1	Data	Data	Data	Data	Data	High
Idle	External	1	1	Float	Data	Address	Data	Data	High
Power-down	Internal	0	0	Data	Data	Data	Data	Data	High
Power-down	External	0	0	Float	Data	Data	Data	Data	High

ABSOLUTE MAXIMUM RATINGS[1, 2, 3]

PARAMETER	RATING	UNIT
Voltage on any other pin to V_{SS}	–0.5 to +6.5	V
Input, output DC current on any single I/O pin	5.0	mA
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.0	W
Storage temperature range	–65 to +150	°C

NOTES:
1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.
2. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.
3. Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

DC ELECTRICAL CHARACTERISTICS

V_{SS}, AV_{SS} = 0V

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS MIN	LIMITS MAX	UNIT
V_{DD}	Supply voltage				
	PCB8XC562		4.0	6.0	V
	PCF8XC562		4.0	6.0	V
	PCA8XC562		4.5	5.5	V
I_{DD}	Supply current operating:	See notes 1 and 2			
	PCB8XC562	f_{OSC} = 16MHz		45	mA
	PCF8XC562	f_{OSC} = 12MHz		34	mA
	PCA8XC562	f_{OSC} = 12MHz		30	mA
I_{ID}	Idle mode:	See notes 1 and 3			
	PCB8XC562	f_{OSC} = 16MHz		10	mA
	PCF8XC562	f_{OSC} = 12MHz		8	mA
	PCA8XC562	f_{OSC} = 12MHz		7	mA
I_{PD}	Power-down current:	See notes 1 and 4; $2V < V_{PD} < V_{DD}$ max			
	PCB8XC562			50	µA
	PCF8XC562			50	µA
	PCA8XC562			100	µA
Inputs					
V_{IL}	Input low voltage, except $\overline{EA}$		–0.5	$0.2V_{DD}$–0.1	V
V_{IL1}	Input low voltage to $\overline{EA}$		–0.5	$0.2V_{DD}$–0.3	V
V_{IH}	Input high voltage, except XTAL1, RST		$0.2V_{DD}$+0.9	V_{DD}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST		$0.7V_{DD}$	V_{DD}+0.5	V
I_{IL}	Logical 0 input current, ports 1, 2, 3, 4	V_{IN} = 0.45V		–50	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3, 4	See note 5		–650	µA
$\pm I_{IL1}$	Input leakage current, port 0, $\overline{EA}$, STADC, $\overline{EW}$	$0.45V < V_I < V_{DD}$		10	µA
Outputs					
V_{OL}	Output low voltage, ports 1, 2, 3, 4	I_{OL} = 1.6mA[6]		0.45	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$, $\overline{PWM0}$, $\overline{PWM1}$	I_{OL} = 3.2mA[6]		0.45	V
V_{OH}	Output high voltage, ports 1, 2, 3, 4	V_{DD} + 5V±10%			
		$-I_{OH}$ = 60µA	2.4		V
		$-I_{OH}$ = 25µA	$0.75V_{DD}$		V
		$-I_{OH}$ = 10µA	$0.9V_{DD}$		V
V_{OH1}	Output high voltage (port 0 in external bus mode, ALE, $\overline{PSEN}$, $\overline{PWM0}$, $\overline{PWM1}$)[7]	V_{DD} + 5V±10%			
		$-I_{OH}$ = 400µA	2.4		V
		$-I_{OH}$ = 150µA	$0.75V_{DD}$		V
		$-I_{OH}$ = 40µA	$0.9V_{DD}$		V
V_{OH2}	Output high voltage (RST)	$-I_{OH}$ = 400µA	2.4		V
		$-I_{OH}$ = 120µA	$0.8V_{DD}$		V
R_{RST}	Internal reset pull-down resistor		50	150	kΩ
C_{IO}	Pin capacitance	Test freq = 1MHz, T_{amb} = 25°C		10	pF

DC ELECTRICAL CHARACTERISTICS (Continued)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS MIN	LIMITS MAX	UNIT
Analog Inputs					
AV_{DD}	Analog supply voltage: PCB8XC562 PCF8XC562 PCA8XC562	 $AV_{DD} = V_{DD} \pm 0.2V$ $AV_{DD} = V_{DD} \pm 0.2V$ $AV_{DD} = V_{DD} \pm 0.2V$	 4.0 4.0 4.5	 6.0 6.0 5.5	 V V V
AI_{DD}	Analog supply current: operating:	Port 5 = 0 to AV_{DD}		1.2	mA
AI_{ID}	Idle mode: PCB8XC562 PCF8XC562 PCA8XC562			 50 50 100	 µA µA µA
AI_{PD}	Power-down mode: PCB8XC562 PCF8XC562 PCA8XC562	$2V < AV_{PD} < AV_{DD}$ max		 50 50 100	 µA µA µA
AV_{IN}	Analog input voltage		AV_{SS}–0.2	AV_{DD}+0.2	V
AV_{REF}	Reference voltage: AV_{REF-} AV_{REF+}		 AV_{SS}–0.2	 AV_{DD}+0.2	 V V
R_{REF}	Resistance between AV_{REF+} and AV_{REF-}		5	25	kΩ
C_{IA}	Analog input capacitance			15	pF
t_{ADS}	Sampling time			$6t_{CY}$	µs
t_{ADC}	Conversion time (including sampling time)			$24t_{CY}$	µs
DL_e	Differential non-linearity[8, 9, 10]			±1	LSB
IL_e	Integral non-linearity[8, 11]			±1	LSB
OS_e	Offset error[8, 12]			±1	LSB
G_e	Gain error[8, 13]			0.4	%
M_{CTC}	Channel to channel matching			±1	LSB
C_t	Crosstalk between inputs of port 5[14]	0–100kHz		–60	dB

NOTES:
1. See Figures 8 through 12 for I_{DD} test conditions.
2. The operating supply current is measured with all output pins disconnected; XTAL1 driven with $t_r = t_f = 10ns$; $V_{IL} = V_{SS} + 0.5V$; $V_{IH} = V_{DD} – 0.5V$; XTAL2 not connected; $\overline{EA}$ = RST = Port 0 = $\overline{EW}$ = V_{DD}; STADC = V_{SS}.
3. The idle mode supply current is measured with all output pins disconnected; XTAL1 driven with $t_r = t_f = 10ns$; $V_{IL} = V_{SS} + 0.5V$; $V_{IH} = V_{DD} – 0.5V$; XTAL2 not connected; Port 0 = $\overline{EW}$ = V_{DD}; $\overline{EA}$ = RST = STADC = V_{SS}.
4. The power-down current is measured with all output pins disconnected; XTAL2 not connected; Port 0 = $\overline{EW}$ = V_{DD}; $\overline{EA}$ = RST = STADC = XTAL1 = V_{SS}.
5. Pins of ports 1, 2, 3, and 4 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2V.
6. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions.
7. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the $0.9V_{DD}$ specification when the address bits are stabilizing.
8. Conditions: $AV_{REF-} = 0V$; $AV_{DD} = 5.0V$, $AV_{REF+} = 5.12V$. ADC is monotonic with no missing codes.
9. The differential non-linearity (DL_e) is the difference between the actual step width and the ideal step width. (See Figure 1.)
10. The ADC is monotonic; there are no missing codes.
11. The integral non-linearity (IL_e) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset error. (See Figure 1.)
12. The offset error (OS_e) is the absolute difference between the straight line which fits the actual transfer curve (after removing gain error), and a straight line which fits the ideal transfer curve. (See Figure 1.)
13. The gain error (G_e) is the relative difference in percent between the straight line fitting the actual transfer curve (after removing offset error), and the straight line which fits the ideal transfer curve. Gain error is constant at every point on the transfer curve. (See Figure 1.)
14. This should be considered when both analog and digital signals are simultaneously input to port 5.

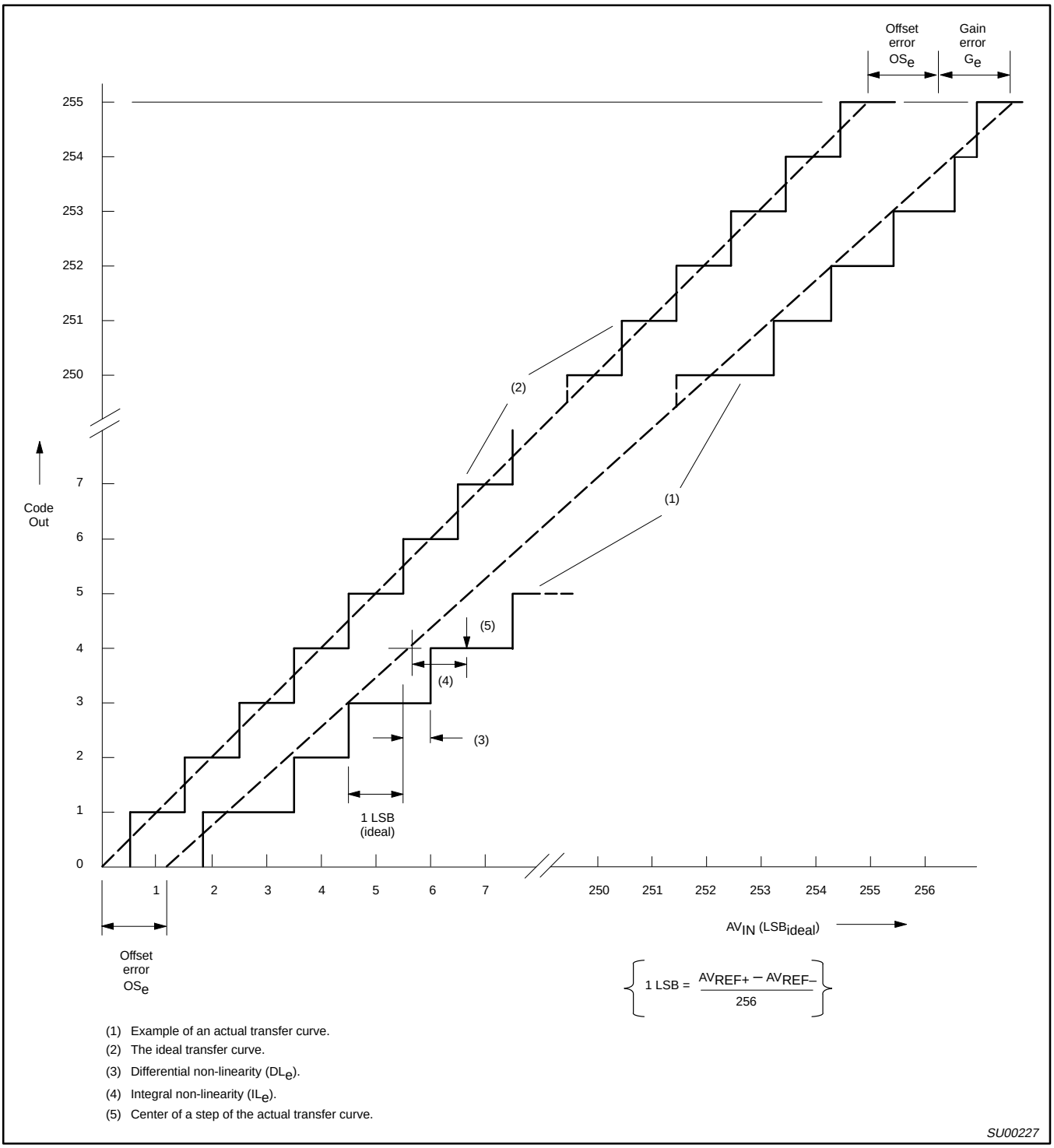


Figure 1. ADC Conversion Characteristic

AC ELECTRICAL CHARACTERISTICS[1, 2]

SYMBOL	FIGURE	PARAMETER	12MHz CLOCK		VARIABLE CLOCK		UNIT
			MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	2	Oscillator frequency			1.2	16	MHz
t_{LHLL}	2	ALE pulse width	127		$2t_{CLCL}-40$		ns
t_{AVLL}	2	Address valid to ALE low	28		$t_{CLCL}-55$		ns
t_{LLAX}	2	Address hold after ALE low	48		$t_{CLCL}-35$		ns
t_{LLIV}	2	ALE low to valid instruction in		234		$4t_{CLCL}-100$	ns
t_{LLPL}	2	ALE low to $\overline{PSEN}$ low	43		$t_{CLCL}-40$		ns
t_{PLPH}	2	$\overline{PSEN}$ pulse width	205		$3t_{CLCL}-45$		ns
t_{PLIV}	2	$\overline{PSEN}$ low to valid instruction in		145		$3t_{CLCL}-105$	ns
t_{PXIX}	2	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	2	Input instruction float after $\overline{PSEN}$		59		$t_{CLCL}-25$	ns
t_{AVIV}	2	Address to valid instruction in		312		$5t_{CLCL}-105$	ns
t_{PLAZ}	2	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{AVLL}	3, 4	Address valid to ALE low	43		$t_{CLCL}-35$		ns
t_{RLRH}	3	$\overline{RD}$ pulse width	400		$6t_{CLCL}-100$		ns
t_{WLWH}	4	$\overline{WR}$ pulse width	400		$6t_{CLCL}-100$		ns
t_{RLDV}	3	$\overline{RD}$ low to valid data in		252		$5t_{CLCL}-165$	ns
t_{RHDX}	3	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	3	Data float after $\overline{RD}$		97		$2t_{CLCL}-70$	ns
t_{LLDV}	3	ALE low to valid data in		517		$8t_{CLCL}-150$	ns
t_{AVDV}	3	Address to valid data in		585		$9t_{CLCL}-165$	ns
t_{LLWL}	3, 4	ALE low to $\overline{RD}$ or $\overline{WR}$ low	200	300	$3t_{CLCL}-50$	$3t_{CLCL}+50$	ns
t_{AVWL}	3, 4	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	203		$4t_{CLCL}-130$		ns
t_{QVWX}	4	Data valid to $\overline{WR}$ transition	23		$t_{CLCL}-60$		ns
t_{DW}	4	Data before $\overline{WR}$	433		$7t_{CLCL}-150$		ns
t_{WHQX}	4	Data hold after $\overline{WR}$	33		$t_{CLCL}-50$		ns
t_{RLAZ}	3	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	3, 4	$\overline{RD}$ or $\overline{WR}$ high to ALE high	43	123	$t_{CLCL}-40$	$t_{CLCL}+40$	ns
External Clock							
t_{CHCX}	5	High time[3]	20		20		ns
t_{CLCX}	5	Low time[3]	20		20		ns
t_{CLCH}	5	Rise time[3]		20		20	ns
t_{CHCL}	5	Fall time[3]		20		20	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
3. These values are characterized but not 100% production tested.

EXPLANATION OF THE AC SYMBOLS

Each timing symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

A – Address
C – Clock
D – Input data
H – Logic level high
I – Instruction (program memory contents)
L – Logic level low, or ALE
P – $\overline{\text{PSEN}}$
Q – Output data
R – $\overline{\text{RD}}$ signal
t – Time
V – Valid
W – $\overline{\text{WR}}$ signal
X – No longer a valid logic level
Z – Float

Examples: t_{AVLL} = Time for address valid to ALE low.
t_{LLPL} = Time for ALE low to $\overline{\text{PSEN}}$ low.

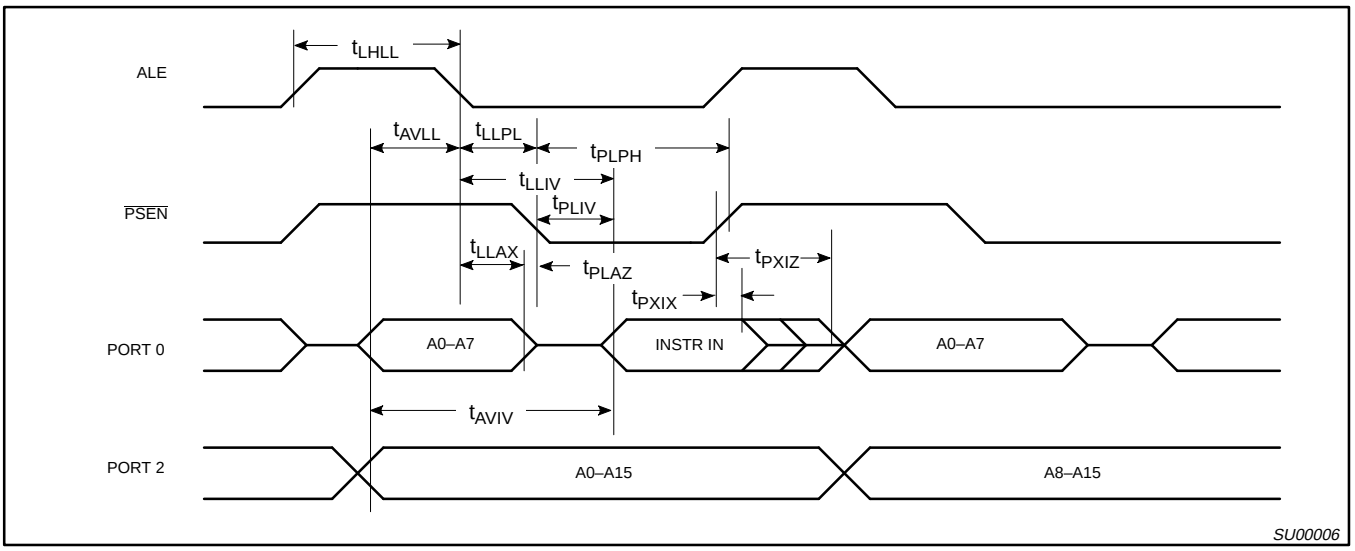


Figure 2. External Program Memory Read Cycle

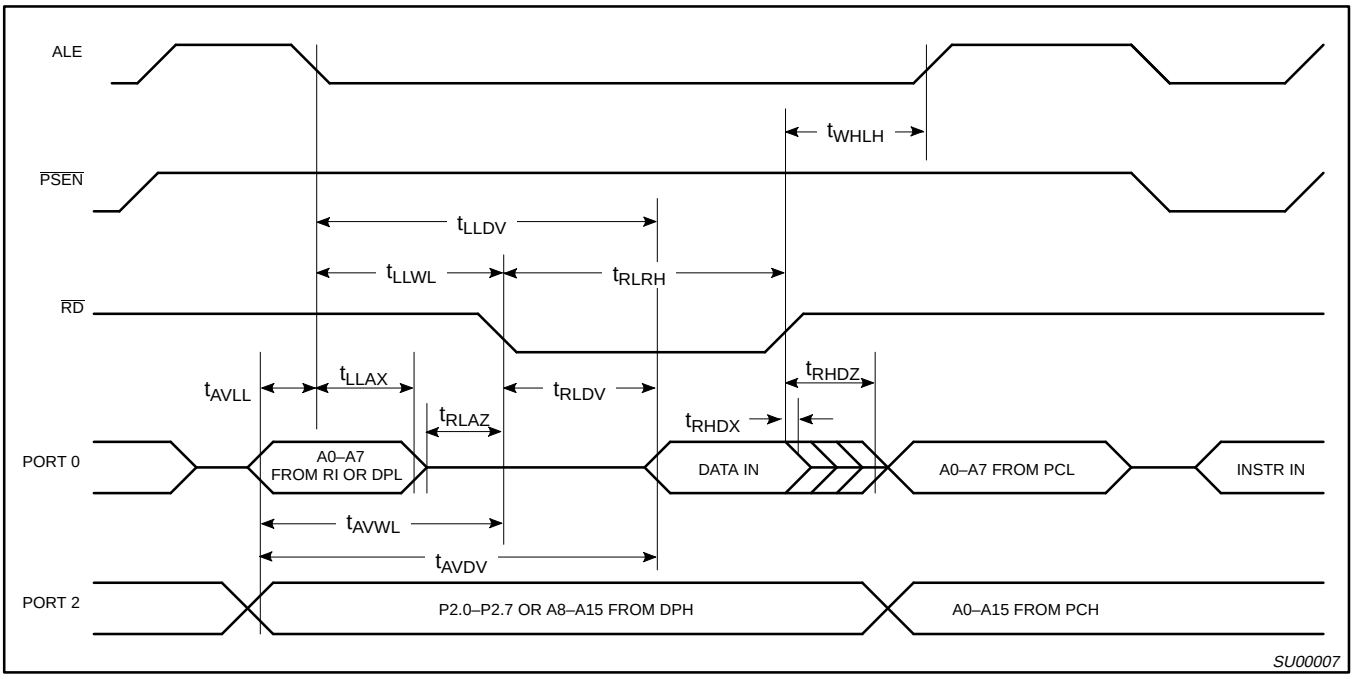


Figure 3. External Data Memory Read Cycle

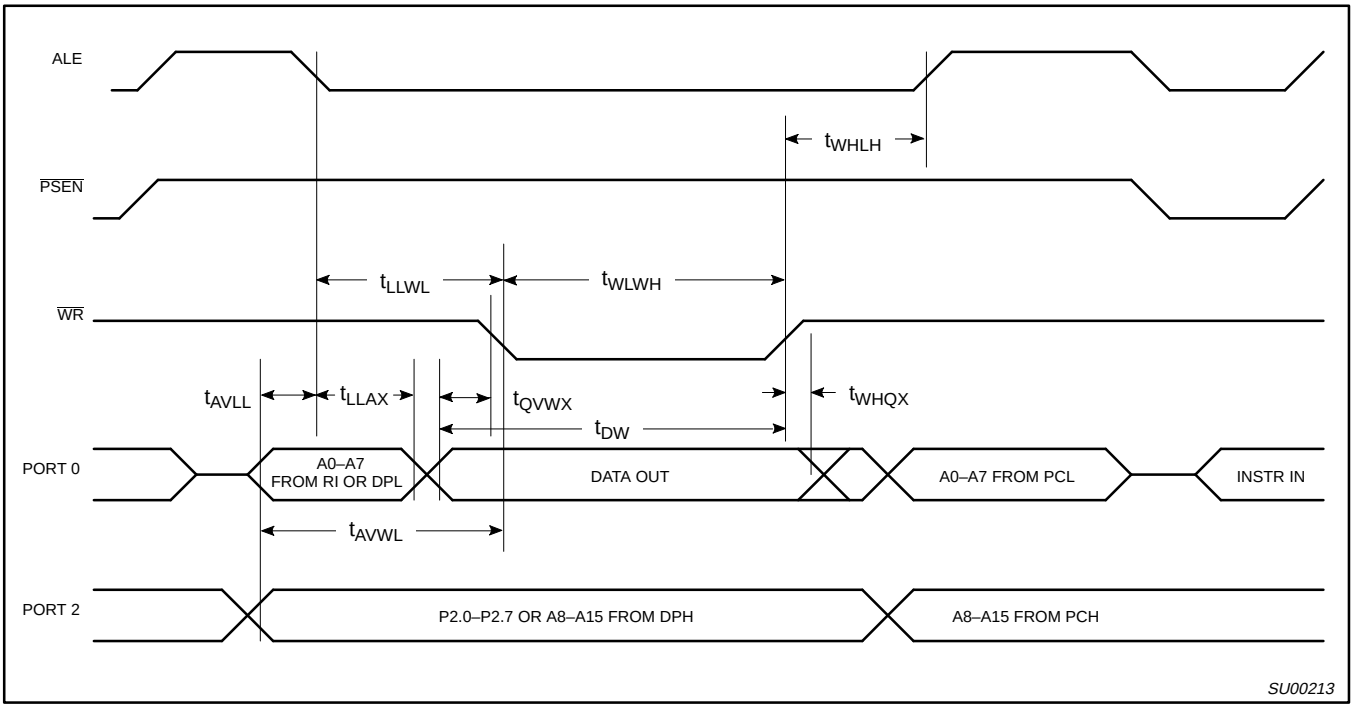


Figure 4. External Data Memory Write Cycle

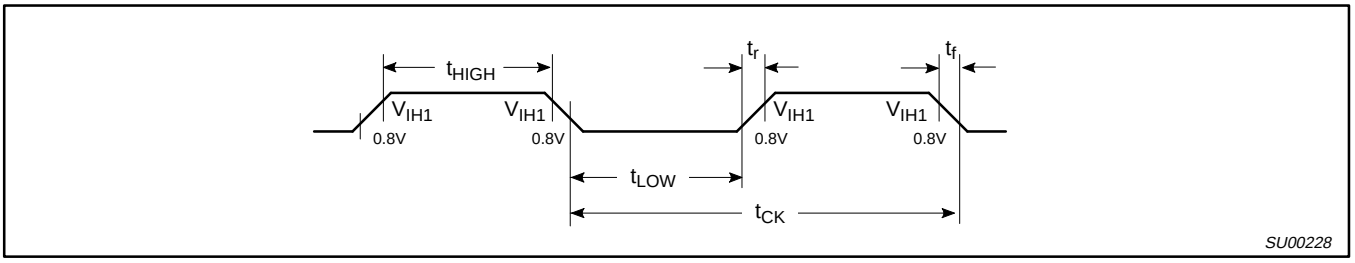


Figure 5. External Clock Drive XTAL1

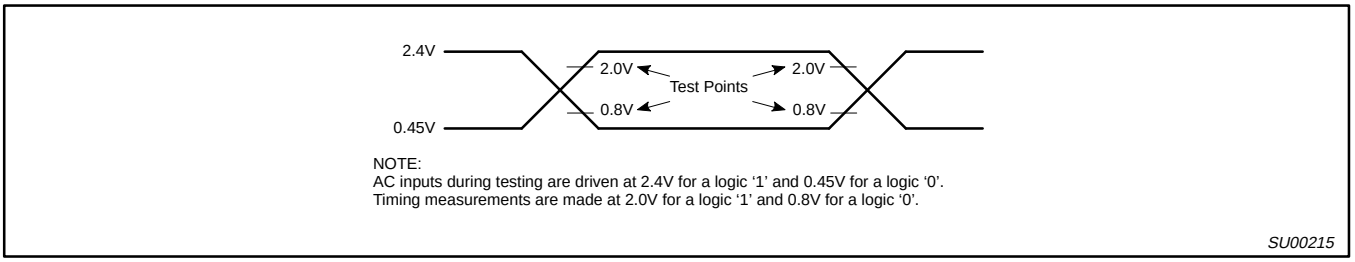


Figure 6. AC Testing Input/Output

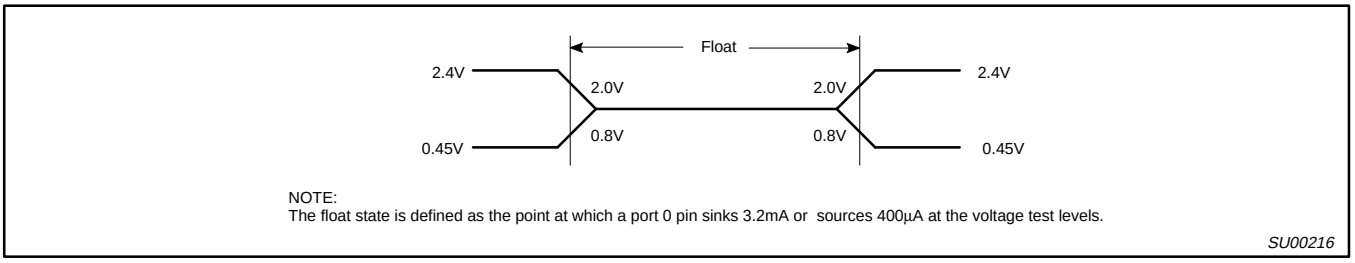
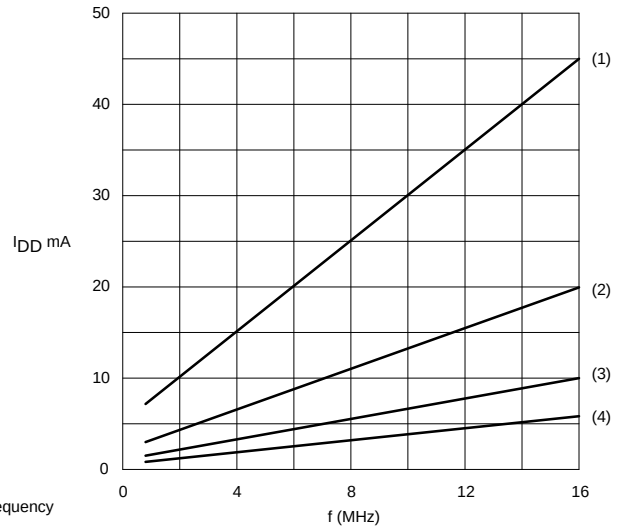


Figure 7. AC Testing Input, Float Waveform

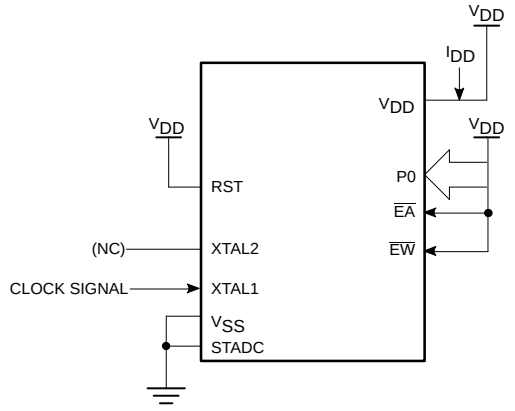


NOTE:
These values are valid only within the frequency specifications of the device under test.

(1) Maximum operating mode; V_{DD} = 6V
(2) Maximum operating mode; V_{DD} = 4V
(3) Maximum idle mode; V_{DD} = 6V
(4) Maximum idle mode; V_{DD} = 4V

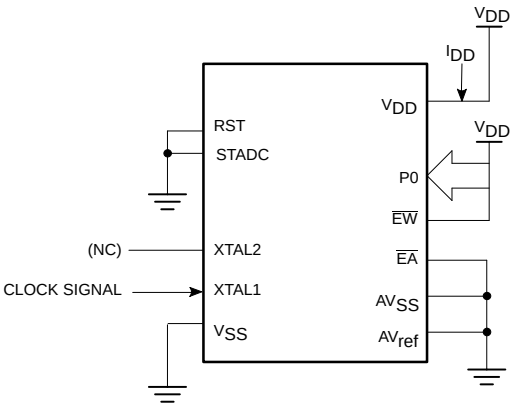
SU00229

Figure 8. Supply Current (I_{DD}) as a Function of Frequency at XTAL1 (f_{OSC})



SU00230

Figure 9. I_{DD} Test Condition, Active Mode
All other pins are disconnected



SU00231

Figure 10. I_{DD} Test Condition, Idle Mode
All other pins are disconnected

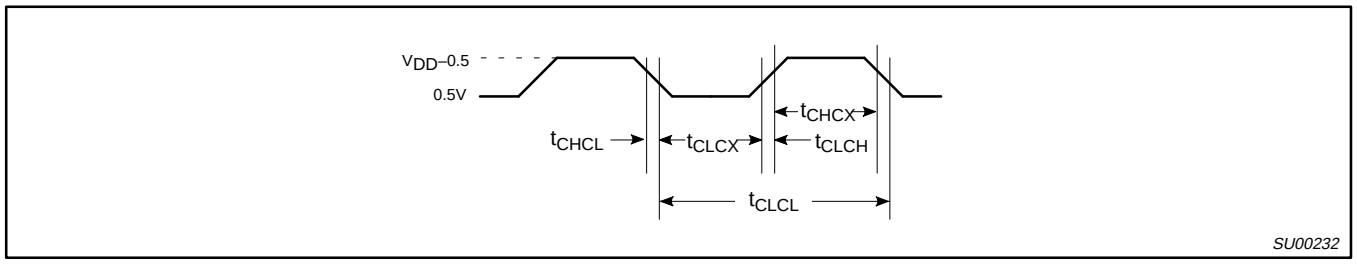


Figure 11. Clock Signal Waveform for I_{DD} Tests in Active and Idle Modes $t_{CLCH} = t_{CHCL} = 10ns$

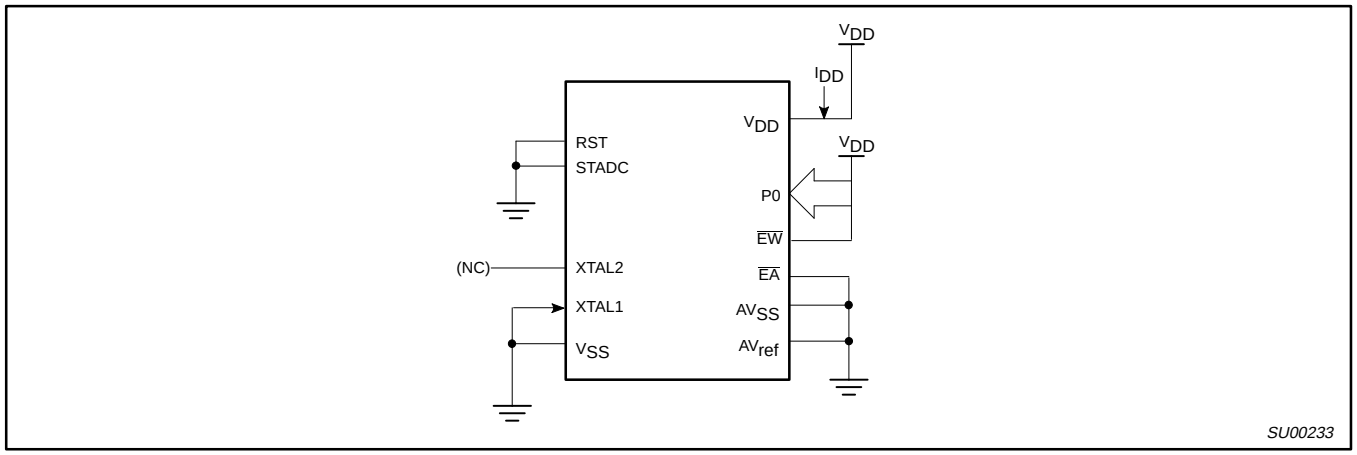
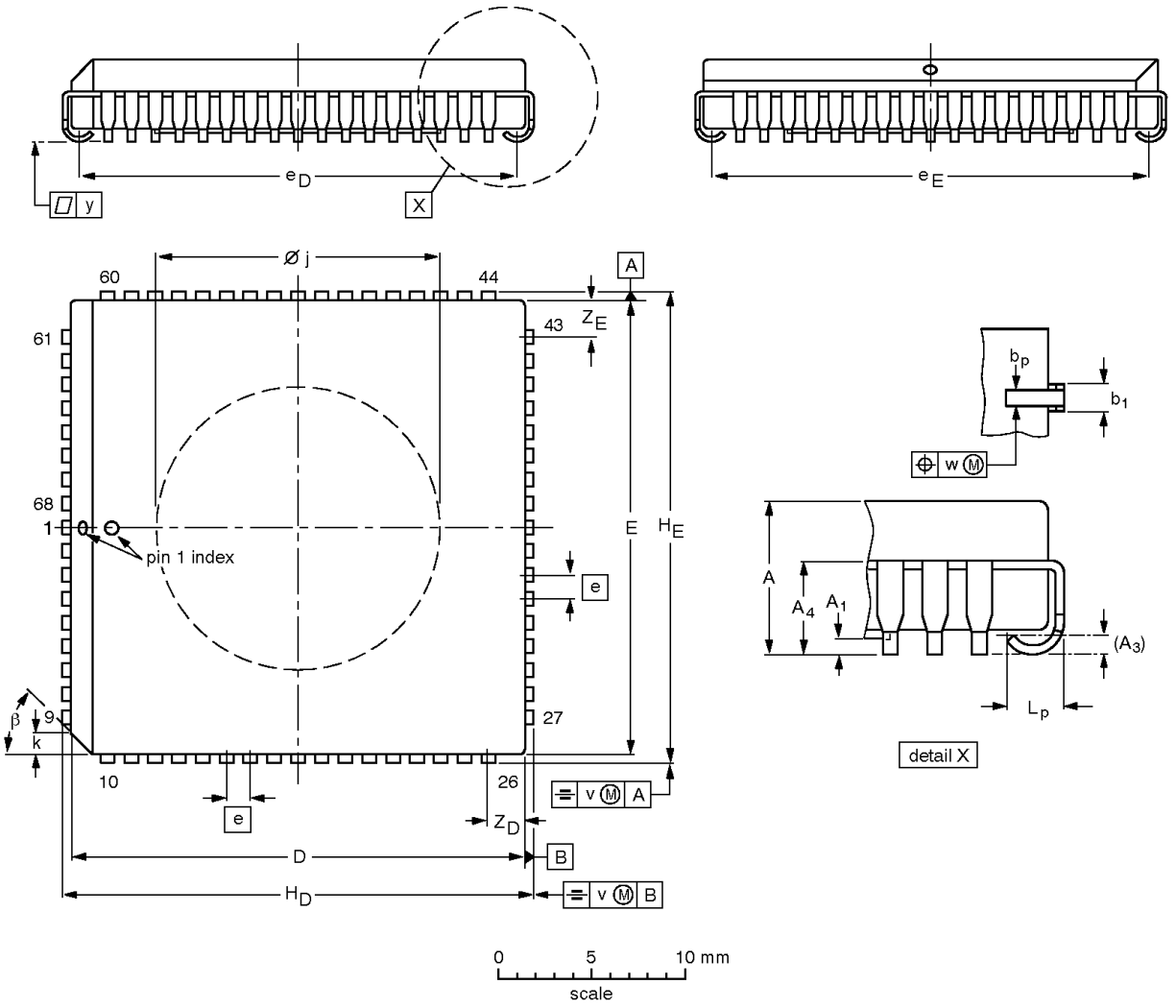


Figure 12. I_{DD} Test Condition, Power Down Mode All other pins are disconnected. V_{DD} = 2V to 5.5V

PLCC68: plastic leaded chip carrier; 68 leads; pedestal SOT188-3



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

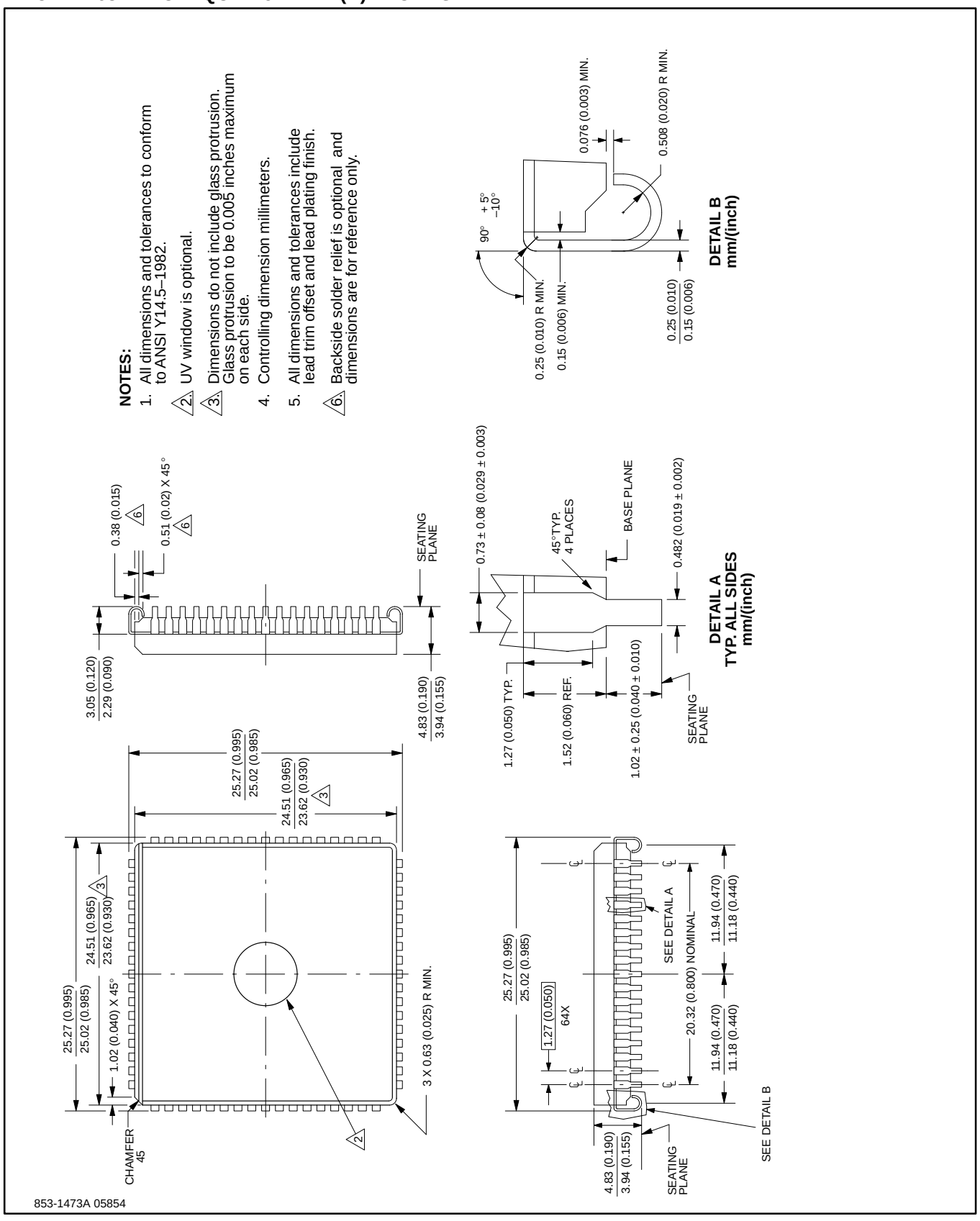
UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	Ø$_j$	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.13	0.25	3.05	0.53 0.33	0.81 0.66	24.33 24.13	24.33 24.13	1.27	23.62 22.61	23.62 22.61	25.27 25.02	25.27 25.02	1.22 1.07	15.34 15.19	1.44 1.02	0.18	0.18	0.10	2.06	2.06	45°
inches	0.180 0.165	0.005	0.01	0.12	0.021 0.013	0.032 0.026	0.958 0.950	0.958 0.950	0.05	0.930 0.890	0.930 0.890	0.995 0.985	0.995 0.985	0.048 0.042	0.604 0.598	0.057 0.040	0.007	0.007	0.004	0.081	0.081	

Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT188-3	112E10	MO-047AE				~~92-11-17~~ 95-02-25

1473A 68-PIN CERQUAD J-BEND (K) PACKAGE



NOTES

NOTES

NOTES

DEFINITIONS

Data Sheet Identification	Product Status	Definition
Objective Specification	**Formative or in Design**	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	**Preproduction Product**	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	**Full Production**	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

Philips Semiconductors
811 East Arques Avenue
P.O. Box 3409
Sunnyvale, California 94088–3409
Telephone 800-234-7381